



Material Content Data Sheet



Sales Product Name		BFR 193W H6327		Issued		4. July 2019		
MA#		MA001612742						
Package		PG-SOT323-3-1		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.01		78	
	noble metal	gold	7440-57-5	0.002	0.03		303	
	inorganic material	silicon	7440-21-3	0.016	0.26	0.30	2615	2996
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1324	
	non noble metal	copper	7440-50-8	2.617	43.95	44.13	439484	441337
wire	noble metal	gold	7440-57-5	0.007	0.12	0.12	1219	1219
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5305	
	plastics	epoxy resin	-	0.679	11.41		114054	
	inorganic material	silicondioxide	60676-86-0	2.448	41.11	53.05	411123	530482
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22285	22285
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1681	1681
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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